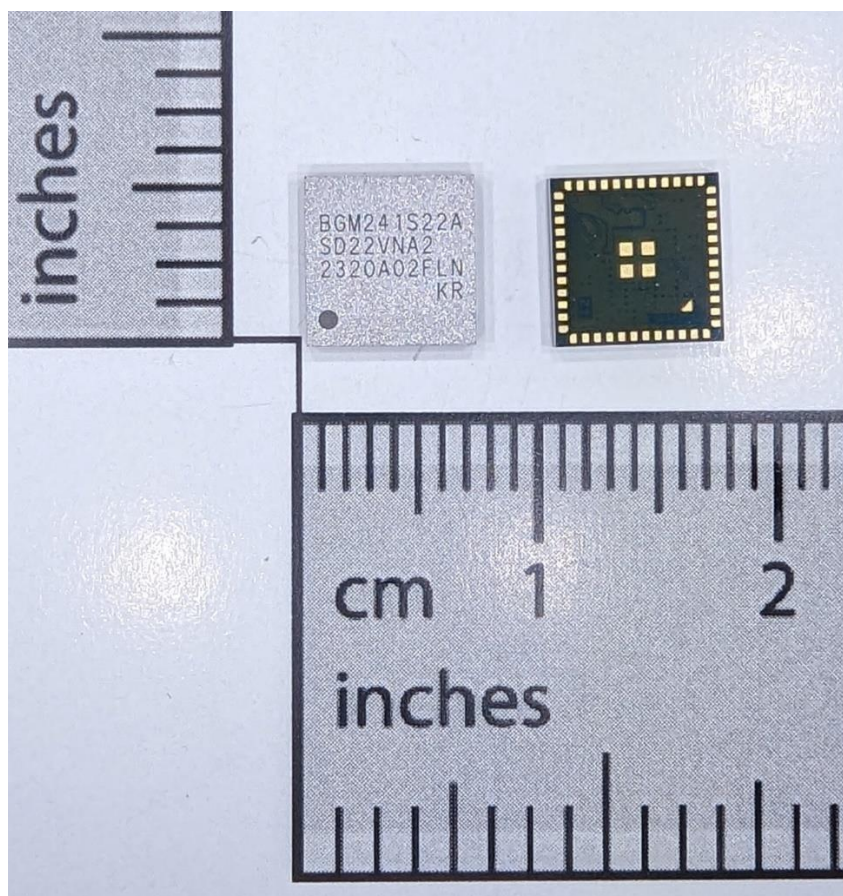


Photos depicting the *Bluetooth Low Energy* wireless radio modules with model name of BGM241S22A (belonging to the xGM24xS22A family of SiP modules)



*Figure 1: Top/Front External View of a BGM241S22A Engineering Sample
(Dimensions: 7 mm x 7 mm x 1.18 mm – Fully Representative of the Production Modules)*



*Figure 2: Top/Front and Bottom/Rear External View of a BGM241S22A Pre-production Sample
(Dimensions: 7 mm x 7 mm x 1.18 mm)*

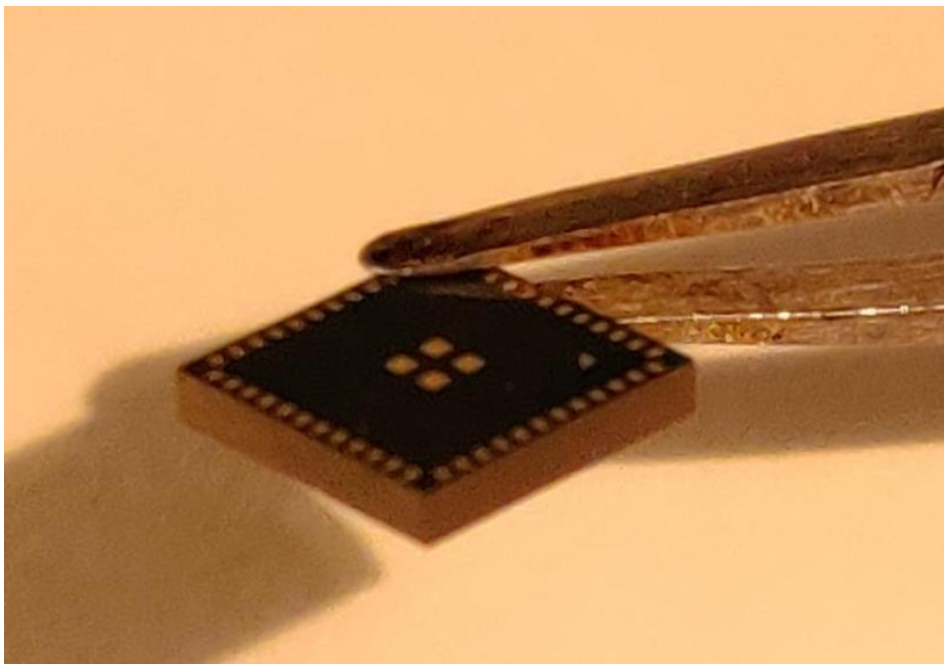
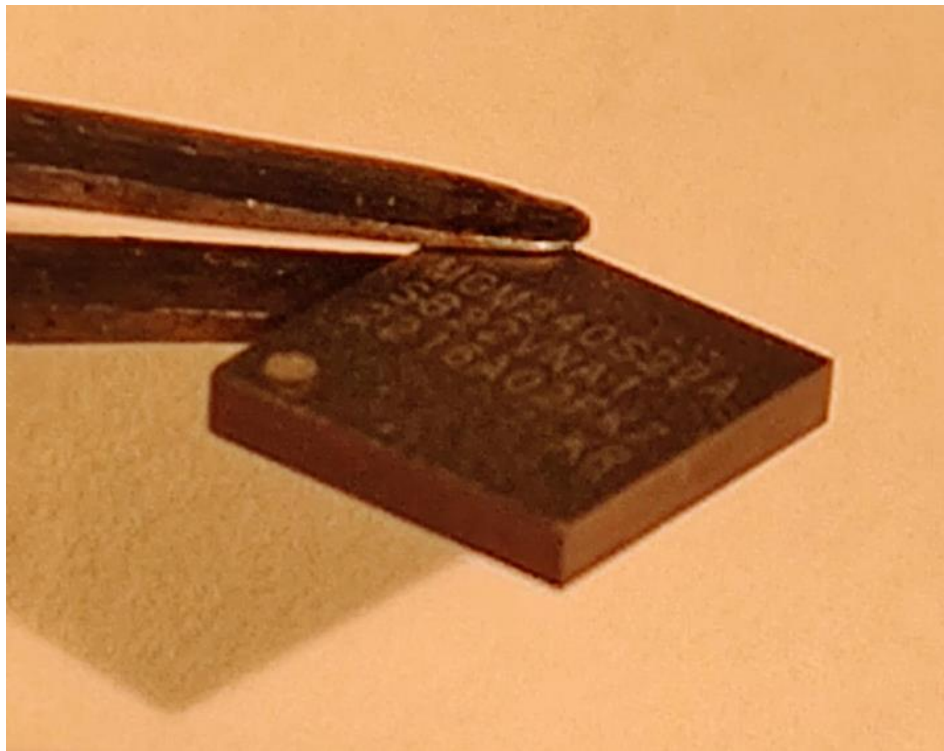


Figure 3 and 4: Details of module's packaging ()*

(*) It shows in particular that all internal components are not accessible because they are enclosed by the molding material which fills all empty spaces (just like any other IC). Integrators and users do not have access to the internals of the module, due to the fact that the module is completely molded and mechanically removing the molding material will destroy the module and break the parts in it.